



N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _C = +25°C
	6mΩ @ V _{GS} = 10V	65A
30V	9.8mΩ @ V _{GS} = 4.5V	55A

Features and Benefits

- Low R_{DS(ON)} Minimizes On-State Losses
- Excellent Q_{gd} x R_{DS(ON)} Product (FOM)
- Advanced Technology for DC-DC Converters
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- 100% Unclamped Inductive Switching Ensures More Reliability
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This MOSFET is designed to minimize the on-state resistance $(R_{DS(ON)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

PowerDI5060-8

- Backlighting
- Power Management Functions
- DC-DC Converters

Mechanical Data

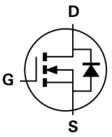
- Case: PowerDI5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 <a>3
- Weight: 0.097 grams (Approximate)



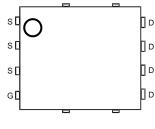




Bottom View



Internal Schematic



Top View Pin Configuration

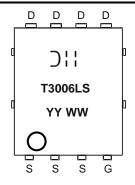
Ordering Information (Note 4)

Part Number	Case	Packaging
DMT3006LPS-13	PowerDI5060-8	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



J;; = Manufacturer's Marking
T3006LS = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 15 = 2015)
WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage	V _{DSS}	30	V	
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Drain Current, V _{GS} = 10V (Note 6)	$T_A = +25$ °C $T_A = +70$ °C	l _D	16 12	А
Continuous Drain Current, $V_{GS} = 10V$ (Note 7) $T_C = +25^{\circ}C$ $T_C = +70^{\circ}C$		l _D	65 50	А
Maximum Continuous Body Diode Forward Current (Note 6	I _S	3	Α	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	100	Α	
Avalanche Current, L=0.1mH (Note 8)	I _{AS}	25	А	
Avalanche Energy, L=0.1mH (Note 8)	Eas	31	mJ	

Thermal Characteristics

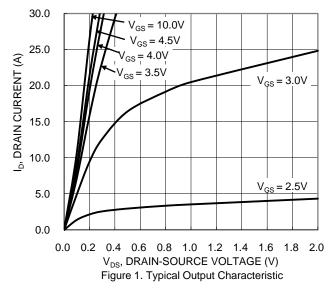
Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	P_{D}	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	99	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	2.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	50	°C/W
Total Power Dissipation (Note 7)	T _C = +25°C	P _D	42	W
Thermal Resistance, Junction to Case (Note 7)		$R_{ heta JC}$	3	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage		30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μA	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = 20V, V_{DS} = 0V$ $V_{GS} = -16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(TH)}	1.0	_	3.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	0	_	4.8	6	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Nesistance	R _{DS(ON)}	_	6.8	9.8		$V_{GS} = 4.5V, I_D = 20A$	
Diode Forward Voltage	V _{SD}	_	0.7	1.0	V	$V_{GS} = 0V, I_{S} = 2A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{iss}		1320	_		V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	490	_	pF		
Reverse Transfer Capacitance	Crss	_	77	_			
Gate Resistance	Rg	_	1.6	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 10V)	Qq	_	22.6	_			
Total Gate Charge (V _{GS} = 4.5V)	Qq	_	10.6	_	nC	$V_{DD} = 15V, I_D = 20A$	
Gate-Source Charge	Q _{qs}	_	3.5	_			
Gate-Drain Charge	Q _{gd}	_	3.5	_			
Turn-On Delay Time	t _{D(ON)}	_	3.5	_		$V_{DD} = 15V, V_{GS} = 10V,$	
Turn-On Rise Time	t _R	_	3.3	_	ns	$R_G = 3\Omega$, $I_D = 20A$	
Turn-Off Delay Time	t _{D(OFF)}	_	13	_			
Turn-Off Fall Time	t _F	_	3.5	_	ns	1 00A d1/dr 500A/c-	
Body Diode Reverse Recovery Charge	Q _{RR}	_	14.4	_	nC	$I_F = 20A$, $dI/dt = 500A/\mu s$	

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
 8. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
 9. Short duration pulse test used to minimize self-heating effect.
 10. Guaranteed by design. Not subject to product testing.





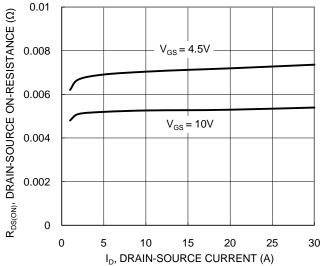


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

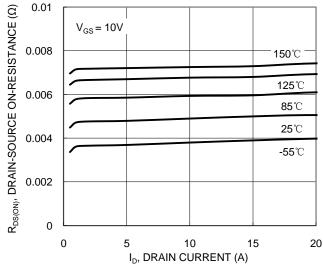
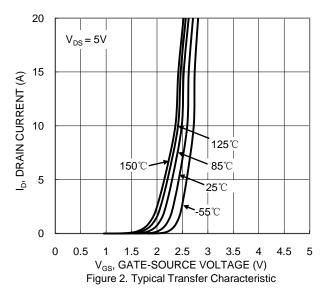
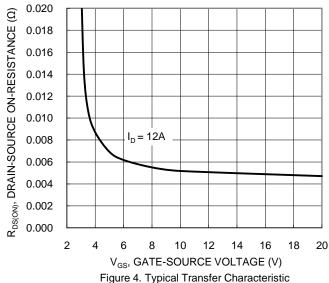


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

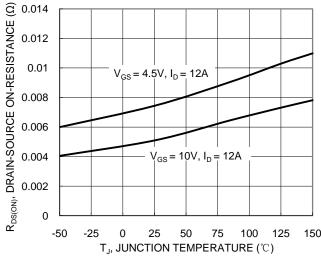


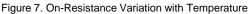


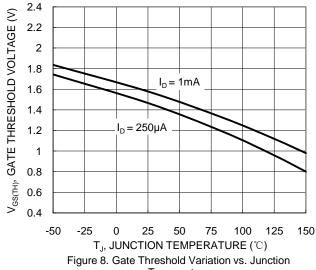
2 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE 1.6 $V_{GS} = 10V, I_{D} =$ (NORMALIZED) 1.2 $V_{GS} = 4.5V, I_{D} = 12A$ 0.8 0.4 -25 0 25 50 75 100 125 -50 150 T_.I, JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Temperature









Temperature

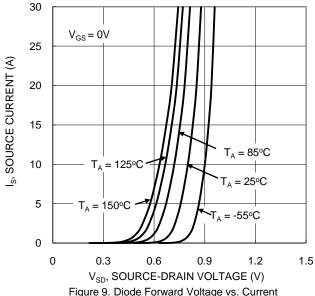
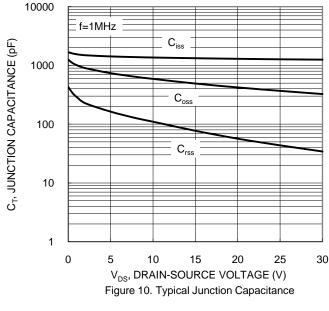
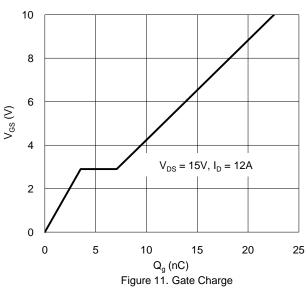
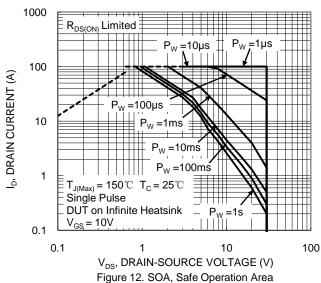


Figure 9. Diode Forward Voltage vs. Current









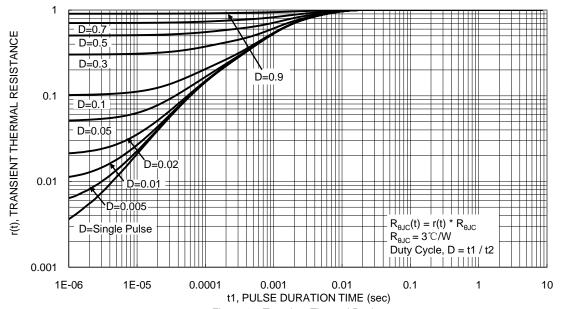


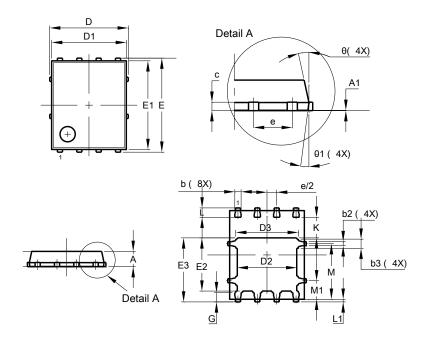
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8

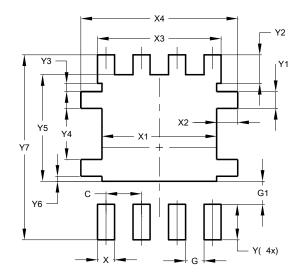


PowerDI5060-8				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0.00	0.05		
b	0.33	0.51	0.41	
b2	0.200	0.350	0.273	
b3	0.40	0.80	0.60	
С	0.230	0.330	0.277	
D	į	5.15 BSC	;	
D1	4.70	5.10	4.90	
D2	3.70	4.10	3.90	
D3	3.90	4.30	4.10	
Е	•	6.15 BSC	;	
E1	5.60	6.00	5.80	
E2	3.28	3.68	3.48	
E3	3.99	4.39	4.19	
е	1.27 BSC			
G	0.51	0.71	0.61	
K	0.51	-	-	
L	0.51	0.71	0.61	
L1	0.100	0.200	0.175	
M	3.235	4.035	3.635	
M1	1.00	1.40	1.21	
Θ	10°	12º	11º	
Θ1	6º	8º	7º	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8



Dimensions	Value (in mm)			
С	1.270			
G	0.660			
G1	0.820			
X	0.610			
X1	4.100			
X2	0.755			
Х3	4.420			
X4	5.610			
Υ	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5	3.810			
Y6	0.180			
Y7	6.610			



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